

Title (en)
METHOD FOR PRODUCING A COMPONENT

Title (de)
VERFAHREN ZUM HERSTELLEN EINES BAUELEMENTS

Title (fr)
PROCEDE DE FABRICATION D'UN COMPOSANT

Publication
EP 1856720 A2 20071121 (DE)

Application
EP 06722565 A 20060301

Priority
• DE 2006000399 W 20060301
• DE 102005010821 A 20050307

Abstract (en)
[origin: WO2006094487A2] The invention relates to a method for producing an electrical and/or optical component. The aim of the invention is to attain a particularly good quality of the component and, in particular, to reliably prevent crystal offsettings in the material layers of the component. To this end, the invention provides a method for producing a component (70, 300, 405) during which at least one trench (30) is etched into a substrate (10). At least one semiconductor layer (50) is laterally grown over said trench so that the trench is completely covered by the semiconductor layer while forming a gas-filled, in particular, air-filled cavity (60). The component is integrated in the semiconductor layer or in an additional semiconductor layer applied to the first semiconductor layer, the active region of the component being located above the cavity.

IPC 8 full level
H01L 21/20 (2006.01); **H01L 33/00** (2010.01); **H01L 33/20** (2010.01)

CPC (source: EP US)
B82Y 20/00 (2013.01 - EP US); **H01L 21/02381** (2013.01 - EP US); **H01L 21/02433** (2013.01 - EP US); **H01L 21/02458** (2013.01 - EP US); **H01L 21/0254** (2013.01 - EP US); **H01L 21/02639** (2013.01 - EP US); **H01L 21/02642** (2013.01 - EP US); **H01L 21/0265** (2013.01 - EP US); **H01L 33/007** (2013.01 - EP US); **H01L 33/20** (2013.01 - EP US); **H01S 5/34333** (2013.01 - EP US); **H01S 5/0207** (2013.01 - EP US); **H01S 5/021** (2013.01 - EP US); **H01S 5/1017** (2013.01 - EP US); **H01S 2301/176** (2013.01 - EP US); **H01S 2304/12** (2013.01 - EP US)

Citation (search report)
See references of WO 2006094487A2

Designated contracting state (EPC)
AT BE BG CH CY CZ DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)
DE 102005010821 A1 20060914; **DE 102005010821 B4 20070125**; EP 1856720 A2 20071121; US 2008048196 A1 20080228; WO 2006094487 A2 20060914; WO 2006094487 A3 20061228

DOCDB simple family (application)
DE 102005010821 A 20050307; DE 2006000399 W 20060301; EP 06722565 A 20060301; US 85190907 A 20070907